

L Number	Hits	Search Text	DB	Time stamp
1	2191	((device or chip or die) with (pad\$2)) and ((test or burn) with substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/28 12:58
2	92	(((device or chip or die) with (pad\$2)) and ((test or burn) with substrate)) and (stabilizer or standoff)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/28 10:28
3	92	(((device or chip or die) with (pad\$2)) and ((test or burn) with substrate)) and (stabilizer or standoff) and (@ad<200006008)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/28 11:42
4	3	(((device or chip or die) with (pad\$2)) and ((test or burn) with substrate)) and ((stabilizer or standoff) with (dielectric or insulat\$4 or photopolymer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/28 11:00
5	1415	((stabilizer or standoff) with (dielectric or insulat\$4 or photopolymer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/28 10:42
6	169	((stabilizer or standoff) with (dielectric or insulat\$4 or photopolymer)) and ((test or burn) and (chip or die or device))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/28 10:40
7	169	(((stabilizer or standoff) with (dielectric or insulat\$4 or photopolymer)) and ((test or burn) and (chip or die or device))) and (@ad<200006008)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/28 10:43
8	406967	((test or burn or KGD) and (IC or chip or die or device))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/28 10:41
9	370	(((test or burn or KGD) and (IC or chip or die or device)) and (((stabilizer or standoff) same (dielectric or insulat\$4 or photopolymer))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/28 10:42
10	370	(((test or burn or KGD) and (IC or chip or die or device)) and (((stabilizer or standoff) same (dielectric or insulat\$4 or photopolymer)))) and (@ad<200006008)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/28 10:51
11	2175	((device or chip or die) with (pad\$2)) and ((test or burn) with substrate) and (@ad<200006008)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/28 11:03
12	185	324/\$.ccls. and standoff	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/28 10:54
13	10	((stabilizer or standoff) with photopolymer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/28 11:00
14	0	((stabilizer or standoff) with photopolymer) and ((device or chip or die) with (test or burn))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/28 11:02

15	722	((device or chip or die) with (pad\$2)) and ((test or burn) with substrate)) and (@ad<200006008)) and (dielectric or photopolymer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/28 11:09
17	724	((device or chip or die) with (pad\$2)) and ((test or burn) with substrate)) and (@ad<200006008)) and (dielectric or photopolymer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/28 11:35
18	12	((device or chip or die) with (pad\$2)) and ((test or burn) with substrate)) and (@ad<200006008)) and photopolymer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/28 11:39
19	542	324/755.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/28 11:39
20	0	324/728.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/28 11:39
22	2902	324/765.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/28 11:39
21	93	324/528.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/28 11:40
23	838	257/48.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/28 11:42
24	830	257/48.cccls. and (@ad<200006008)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/28 11:43
25	742	257/48.cccls. and (@ad<20000608)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/28 12:01
26	120	((device or chip or die) with (pad\$2)) and ((test or burn) with substrate)) and balance	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/28 12:01
27	104	((device or chip or die) with (pad\$2)) and ((test or burn) with substrate)) and balance) and (@ad<20000608)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/28 12:21
28	0	(dielectric near standoff) and ((chip or die) with (test or burn))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/28 12:07
29	1	(dielectric with standoff) and ((chip or die) with (test or burn))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/28 12:18

30	1650	257/773.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/28 12:20
31	1403	257/773.ccls. and (@ad<20000608)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/28 12:43
32	434	(257/773.ccls. and (@ad<20000608)) and pad	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/28 12:38
33	1	6191493.URPN.	USPAT	2002/08/28 12:25
34	8	(257/773.ccls. and (@ad<20000608)) and standoff	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/28 12:38
35	63	((device or chip or die) with balance) and ((test or burn) with substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/28 12:42
36	2287	((device or chip or die) with (stable or collapse)) and (test or burn) and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/28 12:43
37	1939	((device or chip or die) with (stable or collapse)) and (test or burn) and substrate) and (@ad<20000608)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/28 12:45
38	0	standoff adj is	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/28 12:44
40	168	standoff with (enhance or increase or benefit)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/28 12:49
41	153	(standoff with (enhance or increase or benefit)) and (@ad<20000608)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/28 13:06
42	43	standoff with (stabl\$5 or balance)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/28 13:03
43	3010	((device or chip or die) with pad\$2) same (test or burn)) and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/28 13:00
44	0	((device or chip or die) with pad\$2) same (test or burn)) and substrate) and (standoff with (stabl\$5 or balance))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/28 13:13
45	586	((device or chip or die) with pad\$2) same (test or burn)) and substrate) and(stabl\$5 or balance)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/28 13:04

46	161	((device or chip or die) with pad\$2) same (test or burn) and substrate) and ((stabl\$5 or balance) with (chip or die or device))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/28 13:04
47	136	((device or chip or die) with pad\$2) same (test or burn) and substrate) and ((stabl\$5 or balance) with (chip or die or device)) and (@ad<20000608)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/28 13:14
49	67	((device or chip or die) with pad\$2) same (test or burn) and substrate) and ((chip or die) with (stabl\$5 or balance))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/28 13:17
50	55	((device or chip or die) with pad\$2) same (test or burn) and substrate) and ((chip or die) with (stabl\$5 or balance))) and (@ad<20000608)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/28 13:19
51	319	((device or chip or die) with pad\$2) same (test or burn) and substrate) and ((chip or die) with (fall\$3 or bend\$3 or crack\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/28 13:18
52	254	((device or chip or die) with pad\$2) same (test or burn) and substrate) and ((chip or die) with (fall\$3 or bend\$3 or crack\$3))) and (@ad<20000608)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/28 13:19